



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-08
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA756105-8ZT	H88Z*UK99AA6	A	3068	2017-11-08
Amount	UoM	Unit type	ST ECOPACK Grade	
7800.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	28.9-15.5-4.5	27	Through hole	
Comment	PACKAGE OUTLINE FLEXIWATT 27 SMD			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.13	Die	17
Lead	17.51	Soft solder	2245

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	H882*UK99AA6									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	27.502	mg	supplier	die	Silicon (Si)	7440-21-3		26.202	mg	952731	3359				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.173	mg	6290	22				
				supplier	metallization	Tungsten (W)	7440-33-7		0.273	mg	9927	35				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.042	mg	1527	5				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.404	mg	14690	52				
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.015	mg	546	2				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.040	mg	1454	5				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.133	mg	4836	17				
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.017	mg	618	2				
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.203	mg	7381	26				
				Leadframe	Copper & its alloys	5451.402	mg	supplier	alloy	Copper (Cu)	7440-50-8		5444.315	mg	998700	697989
								supplier	alloy	Iron (Fe)	7439-89-6		2.508	mg	460	322
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						4.579	mg	840	587				
Soft solder	Solder	17.962	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	17.513	mg	975003	2245				
				supplier	solder	Silver (Ag)	7440-22-4		0.269	mg	14976	34				
				supplier	solder	Tin (Sn)	7440-31-5		0.180	mg	10021	23				
Bonding wires	Other inorganic materials	2.834	mg	supplier	wire	Copper (Cu)	7440-50-8		2.834	mg	1000000	363				
				supplier	mold compound	Amorphous silica	7631-86-9		1938.306	mg	850000	248501				
Encapsulation	Other Organic Materials	2280.360	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		136.822	mg	60000	17541				
				supplier	mold compound	Phenol resin	proprietary		91.214	mg	40000	11694				
				supplier	mold compound	Mercaptopropyl trimethoxysilane	4420-74-0		6.841	mg	3000	877				
				supplier	mold compound	Other	Proprietary		84.373	mg	37000	10817				
				supplier	mold compound	carbon black	1333-86-4		15.963	mg	7000	2047				
				supplier	mold compound	Bismuth (Bi)	7440-69-9		6.841	mg	3000	877				
Connections coating	Solder	19.940	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		19.940	mg	1000000	2556				